INTEGRATED CIRCUITS

DATA SHEET

74LVT16374A

3.3V LVT 16-bit edge-triggered D-type flip-flop (3-State)

Product data sheet Supersedes data of 2002 Nov 01





3.3V 16-bit edge-triggered D-type flip-flop (3-State)

74LVT16374A

FEATURES

- 16-bit edge-triggered flip-flop
- 3-State buffers
- Output capability: +64 mA/-32 mA
- TTL input and output switching levels
- Input and output interface capability to systems at 5 V supply
- Bus-hold data inputs eliminate the need for external pull-up resistors to hold unused inputs
- Live insertion/extraction permitted
- Power-up reset
- Power-up 3-State
- No bus current loading when output is tied to 5 V bus
- Latch-up protection exceeds 500 mA per JEDEC Std 17
- ESD protection exceeds 2000V per MIL STD 883 Method 3015 and 200V per Machine Model

DESCRIPTION

The 74LVT16374A is a high-performance BiCMOS product designed for V_{CC} operation at 3.3 V.

This device is a 16-bit edge-triggered D-type flip-flop featuring non-inverting 3-State outputs. The device can be used as two 8-bit flip-flops or one 16-bit flip-flop. On the positive transition of the clock (CP), the Q outputs of the flip-flop take on the logic levels set up at the D inputs.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS T _{amb} = 25 °C	TYPICAL	UNIT
t _{PLH} t _{PHL}	Propagation delay nCP to nQx	$C_L = 50 \text{ pF};$ $V_{CC} = 3.3 \text{ V}$	2.9	ns
C _{IN}	Input capacitance	V _I = 0 V or 3.0 V	3	pF
C _{OUT}	Output pin capacitance	Outputs disabled; V _O = 0 V or 3.0 V	9	pF
I _{CCZ}	Total supply current	Outputs disabled; V _{CC} = 3.6 V	70	μА

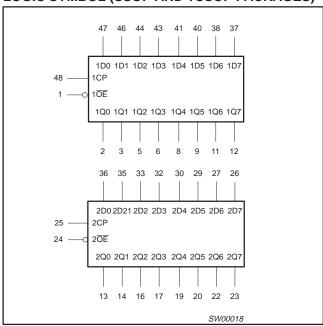
ORDERING INFORMATION

Type number	Package			
	Name	Description	Temperature Range (°C)	Version
74LVT16374ADL	SSOP48	plastic shrink small outline package; 48 leads; body width 7.5 mm	-40 to +85	SOT370-1
74LVT16374ADGG	TSSOP48	plastic thin shrink small outline package; 48 leads; body width 6.1 mm	-40 to +85	SOT362-1
74LVT16374AEV	VFBGA56	plastic very thin fine-pitch ball grid array package; 56 balls; body $4.5 \times 7 \times 0.65$ mm	-40 to +85	SOT702-1

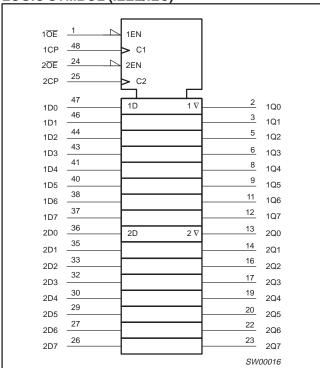
3.3V 16-bit edge-triggered D-type flip-flop (3-State)

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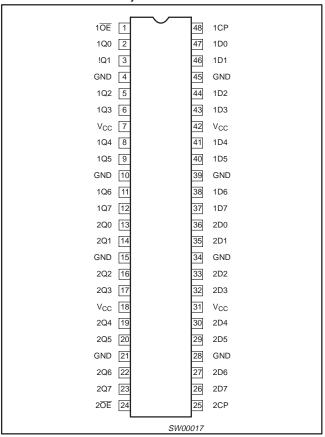
LOGIC SYMBOL (SSOP AND TSSOP PACKAGES)



LOGIC SYMBOL (IEEE/IEC)



PIN CONFIGURATION (SSOP AND TSSOP PACKAGE OPTIONS)



3.3V 16-bit edge-triggered D-type flip-flop (3-State)

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PIN DESCRIPTION (SSOP AND TSSOP PACKAGE **OPTIONS)**

PIN NUMBER	SYMBOL	FUNCTION
47, 46, 44, 43, 41, 40, 38, 37 36, 35, 33, 32, 30, 29, 27, 26	1D0 to 1D7 2D0 to 2D7	Data inputs
2, 3, 5, 6, 8, 9, 11, 12 13, 14, 16, 17, 19, 20, 22, 23	1Q0 to 1Q7 2Q0 to 2Q7	Data outputs
1, 24	1 0E , 2 0E	Output enable inputs (active-LOW)
48, 25	1CP, 2CP	Clock pulse inputs (active rising edge)
4, 10, 15, 21, 28, 34, 39, 45	GND	Ground (0 V)
7, 18, 31, 42	V _{CC}	Positive supply voltage

EV PACKAGE TERMINAL PLACEMENT, TOP VIEW

	1	2	3	4	5	6
А	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc
В	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc
С	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc
D	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc
E	\bigcirc	\bigcirc			\bigcirc	\bigcirc
F	\bigcirc	\bigcirc			\bigcirc	\bigcirc
G	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc
Н	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc
J	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc
K	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc	SR0243

TERMINAL ASSIGNMENTS FOR 74LVT16374A IN VFBGA

	1	2	3	4	5	6
Α	1 OE	NC	NC	NC	NC	1CP
В	1Q1	1Q0	GND	GND	1D0	1D1
С	1Q3	1Q2	Vcc	Vcc	1D2	1D3
D	1Q5	1Q4	GND	GND	1D4	1D5
E	1Q7	1Q6			1D6	1D7
F	2Q0	2Q1			2D1	2D0
G	2Q2	2Q3	GND	GND	2D3	2D2
Н	2Q4	2Q5	Vcc	Vcc	2D5	2D4
J	2Q6	2Q7	GND	GND	2D7	2D6
K	2 OE	NC	NC	NC	NC	2CP

FUNCTION TABLE

	INPUTS		INTERNAL	OUTPUTS	OPERATING MODE
nOE	nCP	nDx	REGISTER	nQ0 to nQ7	OFERATING MODE
L L	<u>†</u>	l h	L H	L H	Load and read register
L	1	Х	NC	NC	Hold
H H	<u></u>	X nDx	NC nDx	Z Z	Disable outputs

H = HIGH voltage level

h = HIGH voltage level one set-up time prior to the HIGH-to-LOW E transition

= LOW voltage level one set-up time prior to the HIGH-to-LOW E transition

NC= No change

X = Don't care

Z = High-impedance "off" state

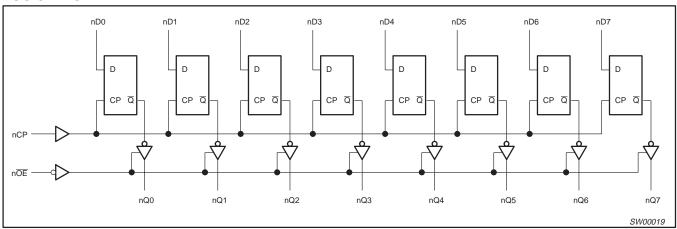
1 = LOW-to-HIGH clock transition

1 = Not a LOW-to-HIGH clock transition

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LOGIC DIAGRAM



ABSOLUTE MAXIMUM RATINGS^{1, 2}

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT	
V _{CC}	DC supply voltage		-0.5 to +4.6	V	
I _{IK}	DC input diode current	V _I < 0 V	-50	mA	
V _I	DC input voltage ³		-0.5 to +7.0	V	
l _{ok}	DC output diode current	V _O < 0 V	-50	mA	
V _{OUT}	DC output voltage ³	Output in Off or HIGH state	-0.5 to +7.0	V	
	DC sustaint surrant	Output in LOW state	128	A	
lout	DC output current	Output in HIGH state	-64	mA	
T _{stg}	Storage temperature range		-65 to +150	°C	

- 1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- 2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150 °C.

 3. The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIM	UNIT	
STWIBOL	FARAINETER	MIN	MAX	UNIT
V _{CC}	DC supply voltage	2.7	3.6	V
VI	Input voltage	0	5.5	V
V _{IH}	HIGH-level input voltage	2.0		V
V _{IL}	Input voltage		0.8	V
I _{OH}	HIGH-level output current		-32	mA
	LOW-level output current		32	A
l _{OL}	LOW-level output current; current duty cycle ≤ 50 %; f ≥ 1 kHz		64	mA
Δt/Δν	Input transition rise or fall rate; Outputs enabled	·	10	ns/V
T _{amb}	Operating free-air temperature range	-40	+85	°C

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DC ELECTRICAL CHARACTERISTICS

SYMBOL PARAMETER				UNIT			
		TEST CONDITIONS			Temp = -		
				MIN	TYP ¹	MAX	
V _{IK}	Input clamp voltage	$V_{CC} = 2.7 \text{ V; } I_{IK} = -18 \text{ mA}$			-0.85	-1.2	V
		$V_{CC} = 2.7 \text{ to } 3.6 \text{ V; } I_{OH} = -100 \mu\text{A}$		V _{CC} -0.2	V _{CC}		
V_{OH}	HIGH-level output voltage	$V_{CC} = 2.7 \text{ V; } I_{OH} = -8 \text{ mA}$		2.4	2.5		V
		V _{CC} = 3.0 V; I _{OH} = -32 mA		2.0	2.3		1
		$V_{CC} = 2.7 \text{ V}; I_{OL} = 100 \mu\text{A}$			0.07	0.2	
		V _{CC} = 2.7 V; I _{OL} = 24 mA			0.3	0.5	1
V_{OL}	LOW-level output voltage	V _{CC} = 3.0 V; I _{OL} = 16 mA			0.25	0.4	٧
		V _{CC} = 3.0 V; I _{OL} = 32 mA			0.3	0.5]
		$V_{CC} = 3.0 \text{ V}; I_{OL} = 64 \text{ mA}$			0.4	0.55]
V_{RST}	Power-up output LOW voltage ⁵	V_{CC} = 3.6 V; I_{O} = 1 mA; V_{I} = GND or V_{CO}	C		0.1	0.55	V
		$V_{CC} = 3.6 \text{ V}; V_I = V_{CC} \text{ or GND}$	Control pins		0.1	±1	
	lanut lankana aumant	V _{CC} = 0 V or 3.6 V; V _I = 5.5 V		0.4	10	μΑ	
ΙΙ	I _I Input leakage current	$V_{CC} = 3.6 \text{ V}; V_{I} = V_{CC}$	Data mine4		0.1	1	μΑ
		V _{CC} = 3.6 V; V _I = 0 V	Data pins ⁴		-0.4	-5	
I _{OFF}	Output off current	$V_{CC} = 0 \text{ V}; V_{I} \text{ or } V_{O} = 0 \text{ V to } 4.5 \text{ V}$			0.1	±100	μΑ
		V _{CC} = 3 V; V _I = 0.8 V		75	135		
I_{HOLD}	Bus Hold current D inputs ⁷	V _{CC} = 3 V; V _I = 2.0 V		-75	-135		μΑ
		V _{CC} = 0 V to 3.6 V; V _{CC} = 3.6 V		±500			1
I _{EX}	Current into an output in the HIGH state when V _O > V _{CC}	V _O = 5.5 V; V _{CC} = 3.0 V			50	125	μΑ
I _{PU/PD}	Power up/down 3-State output current ³	$V_{CC} \le 1.2 \text{ V}; V_O = 0.5 \text{ V to } V_{CC}; V_I = GN$ OE/OE = Don't care	D or V _{CC} ;		1	±100	μА
I _{OZH}	3-State output HIGH current	V_{CC} = 3.6 V; V_{O} = 3.0 V; V_{I} = V_{IH} or V_{IL}			0.5	5	
I _{OZL}	3-State output LOW current	V _{CC} = 3.6 V; V _O = 0.5 V; V _I = V _{IH} or V _{IL}			0.5	- 5	μΑ
Іссн		$V_{CC} = 3.6 \text{ V}$; Outputs HIGH, $V_I = \text{GND or } V_{CC}$, $I_O = 0 \text{ mA}$			0.07	0.12	
I _{CCL}	Quiescent supply current	$V_{CC} = 3.6 \text{ V}$; Outputs LOW, $V_I = \text{GND or } V_{CC}$, $I_O = 0 \text{ mA}$			4	6	mA
I _{CCZ}		Voc = 3.6 V: Outputs Disabled: Vi = GND or Voc		0.07	0.12	1	
Δl _{CC}	Additional supply current per input pin ²	$V_{CC} = 3 \text{ V to } 3.6 \text{ V; One input at } V_{CC} = 0$ Other inputs at V_{CC} or GND	.6 V,		0.1	0.2	mA

- NOTES:
 All typical values are at V_{CC} = 3.3 V and T_{amb} = 25 °C.
 This is the increase in supply current for each input at the specified voltage level other than V_{CC} or GND
 This parameter is valid for any V_{CC} between 0 V and 1.2 V with a transition time of up to 10msec. From V_{CC} = 1.2 V to V_{CC} = 3.3 V ± 0.3 V a transition time of 100 µsec is permitted. This parameter is valid for T_{amb} = 25 °C only.
 Unused pins at V_{CC} or GND.
 For valid test results, data must not be loaded into the flip-flops (or latches) after applying power.
 I_{CCZ} is measured with outputs pulled to V_{CC} or GND.
 This is the bus hold overdrive current required to force the input to the opposite logic state.

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AC CHARACTERISTICS

GND = 0 V; t_R = t_F = 2.5 ns; C_L = 50 pF; R_L = 500 Ω ; T_{amb} = -40 °C to +85 °C.

				LI	MITS		
SYMBOL	PARAMETER	WAVEFORM	V _{CC}	= 3.3 V \pm 0	.3 V	V _{CC} = 2.7 V	UNIT
			MIN	TYP ¹	MAX	MAX	
f _{max}	Maximum clock frequency	1	150				MHz
t _{PLH} t _{PHL}	Propagation delay nCP to nQx	1	1.5 1.5	2.9 3.0	5.0 5.0	5.6 5.6	ns
t _{PZH} t _{PZL}	Output enable time to HIGH and LOW level	3 4	1.5 1.5	3.2 3.0	4.8 4.6	6.0 5.2	ns
t _{PHZ} t _{PLZ}	Output disable time from HIGH and LOW Level	3 4	1.5 1.5	3.9 3.4	5.4 4.6	6.0 5.0	ns

NOTE:

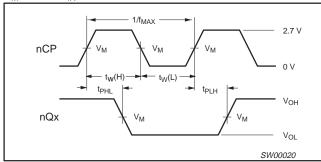
AC SETUP REQUIREMENTS

GND = 0 V; t_R = t_F = 2.5 ns; C_L = 50 pF; R_L = 500 Ω ; T_{amb} = -40 °C to +85 °C.

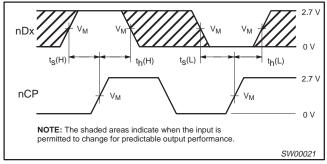
				LIMITS		
SYMBOL	PARAMETER	WAVEFORM	V _{CC} = 3.3	$V \pm 0.3 V$	$V_{CC} = 2.7 \text{ V}$	UNIT
			MIN	TYP	MIN	
t _S (H) t _S (L)	Setup time nDx to nCP	2	2.0 2.0	0.7 0.7	2.0 2.0	ns
t _h (H) t _h (L)	Hold time nDx to nCP	2	0.8 0.8	0 0	0.1 0.1	ns
t _W (H) tw(L)	nCP pulse width HIGH or LOW	1	1.5 3.0	0.6 1.6	1.5 3.0	ns

AC WAVEFORMS

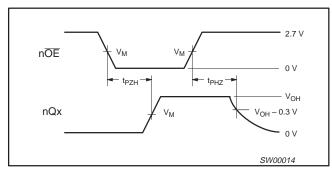
 $V_M = 1.5 \text{ V}, V_{IN} = \text{GND to } 3.0 \text{ V}$



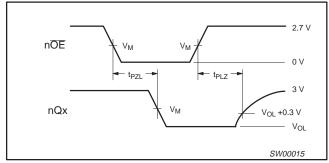
Waveform 1. Propagation delay, clock input to output, clock pulse width, and maximum clock frequency



Waveform 2. Data setup and hold times



Waveform 3. 3-State Output Enable time to HIGH level and Output Disable time from HIGH level



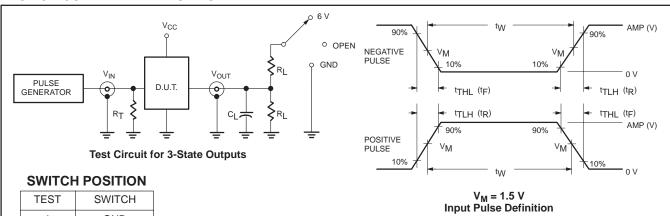
Waveform 4. 3-State Output Enable time to LOW level and Output Disable time from LOW level

^{1.} All typical values are at V_{CC} = 3.3 V and T_{amb} = 25 °C.

3.3V 16-bit edge-triggered D-type flip-flop (3-State)

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TEST CIRCUIT AND WAVEFORMS



TEST	SWITCH
t _{PHZ} /t _{PZH}	GND
t _{PLZ} /t _{PZL}	6 V
t _{PLH} /t _{PHL}	open

DEFINITIONS

R_L = Load resistor; see AC CHARACTERISTICS for value.

 $C_L = Load$ capacitance includes jig and probe capacitance; see AC CHARACTERISTICS for value.

 R_T = Termination resistance should be equal to Z_{OUT} of pulse generators.

FAMILY	IN	PUT PULSE R	EQUIRE	MENTS	
FAIVIILT	Amplitude	Rep. Rate	t _W	t _R	t _F
74LVT16	2.7 V	≤10 MHz	500 ns	≤2.5 ns	≤2.5 ns

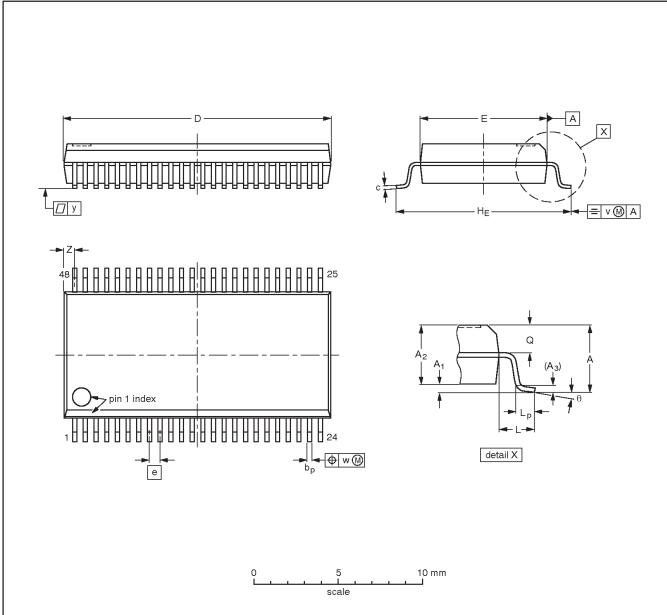
SW00003

3.3V 16-bit edge-triggered D-type flip-flop (3-State)

74LVT16374A

SSOP48: plastic shrink small outline package; 48 leads; body width 7.5 mm

SOT370-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	2.8	0.4 0.2	2.35 2.20	0.25	0.3 0.2	0.22 0.13	16.00 15.75	7.6 7.4	0.635	10.4 10.1	1.4	1.0 0.6	1.2 1.0	0.25	0.18	0.1	0.85 0.40	8° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

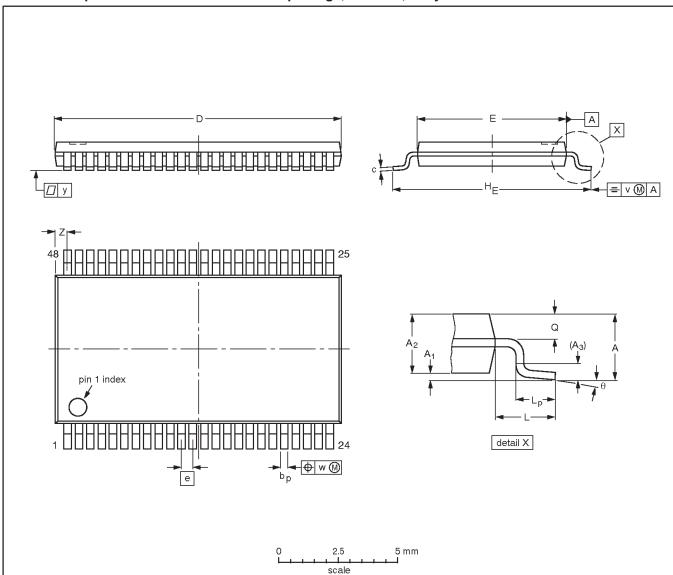
OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE	
SOT370-1		MO-118			99-12-27 03-02-19	

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TSSOP48: plastic thin shrink small outline package; 48 leads; body width 6.1 mm

SOT362-1



DIMENSIONS (mm are the original dimensions).

UNIT	A max.	Α1	A ₂	Α3	bp	С	D ⁽¹⁾	E ⁽²⁾	е	HE	L	Lp	Q	v	w	у	z	θ
mm	1.2	0.15 0.05	1.05 0.85	0.25	0.28 0.17	0.2 0.1	12.6 12.4	6.2 6.0	0.5	8.3 7.9	1	0.8 0.4	0.50 0.35	0.25	0.08	0.1	0.8 0.4	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

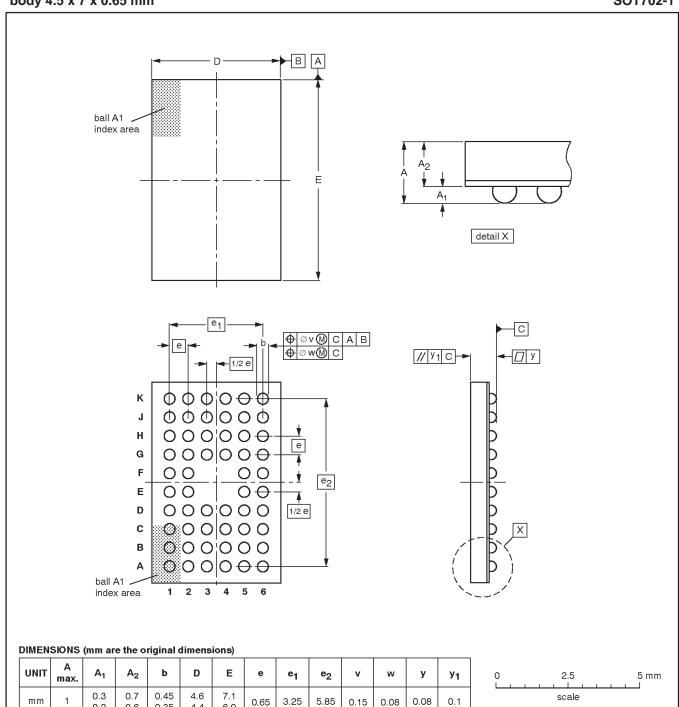
OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT362-1		MO-153				99-12-27 03-02-19

3.3V 16-bit edge-triggered D-type flip-flop (3-State)

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VFBGA56: plastic very thin fine-pitch ball grid array package; 56 balls; body $4.5\ x\ 7\ x\ 0.65\ mm$

SOT702-1



OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE	
SOT702-1		MO-225			-02-08-08 03-07-01	

3.3V 16-bit edge-triggered D-type flip-flop (3-State)

74LVT16374A

REVISION HISTORY

Rev	Date	Description
_5	20040916	Product data sheet (9397 750 14077). Supersedes data of 2002 Nov 01 (9397 750 10649).
		Modifications:
		AC Setup Requirements table on page 7:
		$- V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$
		change t _s (H) and t _s (L) setup time nDx to nCP Min. from 2.5 ns to 2.0 ns
		change t _h (H) and t _h (L) hold time nDx to nCP Min. from 0.5 ns to 0.8 ns
		$- V_{CC} = 2.7 \text{ V}$
		change t _s (H) and t _s (L) setup time nDx to nCP Min. from 2.5 ns to 2.0 ns
		change t _h (H) and t _h (L) hold time nDx to nCP Min. from 0 ns to 0.1 ns
_4	20021101	Product data (9397 750 10649); supersedes Product specification 74LVT16374A_3 of 1999 Oct 18 (9397 750 06514)
		Engineering Change Notice 853–1781 29140 (date: 20021101)

3.3V 16-bit edge-triggered D-type flip-flop (3-State)

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Data sheet status

Level	Data sheet status [1]	Product status ^[2] [3]	Definitions
I	Objective data sheet	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data sheet	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
III	Product data sheet	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

^[1] Please consult the most recently issued data sheet before initiating or completing a design.

Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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^[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

^[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.